

Title (en)

MATERIAL FOR METAL POROUS BODY AND METAL POROUS BODY

Title (de)

MATERIAL FÜR EINEN PORÖSEN METALLKÖRPER UND PORÖSER METALLKÖRPER

Title (fr)

MATÉRIAU POUR UN CORPS POREUX MÉTALLIQUE ET CORPS POREUX MÉTALLIQUE

Publication

**EP 3769868 A1 20210127 (EN)**

Application

**EP 19771114 A 20190116**

Priority

- JP 2018056167 A 20180323
- JP 2019001073 W 20190116

Abstract (en)

A material for porous metal body having a coil shape of a wire material wound in a helical shape, made of metal which having good thermal conductivity and can join by sintering; an average wire diameter  $D_w$  of the wire material is 0.05 mm to 2.00 mm inclusive, an average coil outer diameter  $D_c$  is 0.5 mm to 10.0 mm inclusive, a coil length  $L$  of 1 mm to 20 mm inclusive, and a winding number  $N$  is 1 to 10; and the plurality of materials for porous metal body are combined and sintered to form a metal porous body having a plurality of pores so that a pore ratio of the metal porous body is facilitated to be controlled.

IPC 8 full level

**B22F 3/11** (2006.01)

CPC (source: EP US)

**B22F 3/002** (2013.01 - EP); **B22F 3/10** (2013.01 - EP); **B22F 3/11** (2013.01 - US); **B22F 3/1103** (2013.01 - EP); **B22F 8/00** (2013.01 - EP); **C22C 1/08** (2013.01 - EP US); **D07B 1/0693** (2013.01 - US); **B21C 47/02** (2013.01 - US); **B21F 3/02** (2013.01 - US); **B22F 2005/004** (2013.01 - EP); **B22F 2301/052** (2013.01 - US); **B22F 2998/10** (2013.01 - EP); **H01B 7/226** (2013.01 - US); **Y02W 30/50** (2015.05 - EP); **Y10T 428/12333** (2015.01 - US); **Y10T 428/2925** (2015.01 - US)

Designated contracting state (EPC)

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Designated extension state (EPC)

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**EP 3769868 A1 20210127**; **EP 3769868 A4 20211006**; CN 111801188 A 20201020; JP 2019167580 A 20191003; JP 7010105 B2 20220126; US 11590570 B2 20230228; US 2021023623 A1 20210128; WO 2019181157 A1 20190926

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